



## Material Content Data Sheet



Sales Product Name	TLE7231G			Issued		28. August 2013		
MA#	MA000982040							
Package	PG-DSO-14-1			Weight*		143.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.214	2.24	2.24	22432	22432
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		421	
	non noble metal	iron	7439-89-6	1.207	0.84		8424	
	non noble metal	copper	7440-50-8	49.007	34.20	35.09	342048	350998
wire	noble metal	gold	7440-57-5	0.385	0.27	0.27	2685	2685
encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1199	
	plastics	epoxy resin	-	7.899	5.51		55131	
	inorganic material	silicondioxide	60676-86-0	77.787	54.30	59.93	542924	599254
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8558	8558
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7187	7187
glue	plastics	acrylic resin	-	0.280	0.20		1955	
	noble metal	silver	7440-22-4	0.993	0.69	0.89	6931	8886
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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